

03-27-01

A



NON-PROVISIONAL APPLICATION FOR U. S. PATENT UNDER 37 CFR 1.53(b) TRANSMITTAL FORM

Attorney Docket No. TI-30589

Assistant Commissioner for Patents
Washington, D. C. 20231

Sir:

Transmitted herewith for filing is the
patent application of:

Inventor(s): **Howard R. Test**
Gonzalo Amador
Willmar E. Subido

For: **Wire Bonding process for Copper-Metallized Integrated Circuits**
Enclosed are:

- 2 Sheets of formal drawings and 21 pages of Specification (including Abstract)
- x A Declaration/Power of Attorney
- x Assignment with form PTO 1595

"EXPRESS MAILING" Mailing Label No.

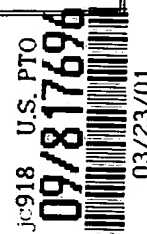
EL 769269082 US. Date of Deposit: March 23, 2001.

I hereby certify that this paper is being deposited with the
U.S. Postal Service Express Mail Post Office to Addressee
Service under 37 CFR 1.10 on the date shown above and is
addressed to the Assistant Commissioner for Patents,
Washington, D.C. 20231.

Glenda West

Glenda West

03/23/01



Please amend the specification by inserting before the first line the sentence:

This application claims priority under 35 USC § 119 based upon **Provisional Patent Application number 60,192,108, filed 03/24/2000.**

FEE CALCULATION					FEE
	NUMBER		NUMBER EXTRA	RATE	BASIC FEE \$ 710.00
Total Claims	15	-20 =	0	X \$22 =	0.00
Independent Claims	2	- 3 =	0	X \$82 =	00.00
Total Filing Fee					\$ 710.00

Please charge **Deposit Account No. 20-0668** in the amount of the Total Fees set forth. The Commissioner is hereby authorized to charge any additional fees which may be required, or credit any overpayment to Deposit Account No. 20-0668. This form is submitted in triplicate.

All correspondence related to this application may be addressed to the undersigned at Navarro IP Law Group, P.C. 801 E. Campbell Rd. Suite 655, Richardson, TX 75081.

Date: March 23, 2001

Gary C. Hough
Registration No. 20,750



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March 23, 2001

VIA EXPRESS MAIL

EL 769269082US



Assistant Commissioner for Patents
Washington, D.C. 20231

Re: Patent Application for
"Wire Bonding Process for Copper-Metallized Integrated Circuits"
Attorney Docket No. TI-30589
Our File: 1000-2140

Dear Sir:

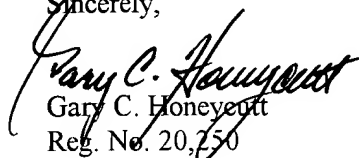
Enclosed for filing please find the following items relating to the above-identified application:

- (1) Declaration, and Power of Attorney;
- (2) Non-Provisional Application;
- (3) Fee Authorization/transmittal Form ;
- (4) Recordation Form Cover Sheet with Assignment;
- (5) Specifications and Formal Drawings; and
- (6) Postcards.

Please charge **Deposit Account No. 20-0668** in the amount of the total fees set forth. The Commissioner is hereby authorized to charge any additional fees which may be required, or credit any overpayment to **Deposit Account No. 20-0668**.

Please file the application and return the date-stamped postcard to the corresponding addresses as indicated. In the meantime, if you have any questions or comments concerning this matter, please call the undersigned. Otherwise, please accept the enclosed.

Sincerely,


Gary C. Honeycutt
Reg. No. 20,250

GCH/gw
Enclosures